

## Application Data Sheet

### Application Information

Application Type::	Regular
Subject Matter::	Utility
CD-ROM or CD-R?	None
Title::	Structures For Improving Heat Dissipation In Stacked Semiconductor Packages
Attorney Docket Number::	AMK-11317-1D
Request for Early Publication?::	No
Request for Non-Publication?::	Yes
Suggested Drawing Figure::	1
Total Drawing Sheets::	10
Small Entity::	No
Petition included?::	No
Secrecy Order in Parent Appl.?::	No

### Applicant Information

Applicant Authority type::	Inventor
Primary Citizenship Country::	US
Status::	Full Capacity
Given Name::	Paul
Middle Name::	Robert
Family Name::	Hoffman
City of Residence::	Chandler
State or Province of Residence::	AZ
Country of Residence::	US
Street of mailing address::	1961 West Hemlock Way
Country of mailing address::	US
Postal or Zip Code of mailing address::	85248

**Applicant Information**

Applicant Authority type:: Inventor  
Primary Citizenship Country:: US  
Status:: Full Capacity  
Given Name:: David  
Middle Name:: Albert  
Family Name:: Zoba  
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**Correspondence Information**

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**Representative Information**

Representative Customer Number:: 022888

**Domestic Priority Information**

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This application	is a Divisional of	10/013,396	12/7/01

**Assignee Information**

Assignee Name:: Amkor Technology, Inc.  
Street of mailing address:: 1900 South Price Road  
City of mailing address:: Chandler  
State of Province of mailing address:: AZ  
Country of of mailing address:: US  
Postal or Zip Code of mailing address:: 85248